

azo dyes; alkane thiols, Alloxazine; 2-Aminopyrimidine; 2-Amino-1,3,4, thiadiazole; Amino methyl thiadiazole; 2-Aminothiadiazole; 3-amino 1,2,4, triazole; benzal acetone, Benzopurpurin; benzophnon, Behzotriazole, hydroxylbenzotriazole, Betizyldene acetone, Benzoic acid, Benzoil acetic acid ethyl ester, Boric acid, cacodylic acid, Corcumin Pyonin Y; Carminic Acid; Cinamic aldehyde, cocobetaine or decyl betaine, cetyl betaine, cysteine; DETA-PAC; 2',7'-dichlorofluorescein; dextrose, dicarboxylic amino acids; dipeptide diaminoacid (camsine=beta alanyl hystadine), 5-p-dimethylamine benzyldene Rhodamine, 5-(p-Dimethylamino-benzyldene)-2-thio barbituric, dithizone, 4-(p-Ethoxyphenylazo)-m-phenylendi-amine, ethoxilated tetramethyl decynediol, ethoxilated quaternary amonium salts, ethyl benzoil acetate, ethoxilated betanaphthol, EDTA, Evan Blue; di ethylene triamine penta acetic acid or salts, diethylenetriamine pentaacetate, penta sodium salt, glucamine, glycerol compounds, di-glycine, d-glucamine, triglycine, glycogen, glutar aldehyde, glutamic acid, its salts and esters (MSG), sodium glucoheptonate, hydroxylbenzotriazole, hydroxysuccinimide, hydantoin, 4-(8-Hydroxy-5-quinolylazo)-1-napthalenesulfonic acid, p-(p-hydroxyphenylazo) benzene sulfonic, insulin, hydroxybenzaldehyde, imidazoline; lignosulfonates; methionine; mercaptobenzi-imidazoles; Martius Yellow; 2-methyl-1-p-tolyltriazene, 3-(p-Nitrophenyl)-1-(p-phenylazophnyl)triazene; 4-(p-Nitrophenylazo) resorcinol, 4-(p-Nitrophenylazo)-1-naphthol, OCBA-orthochloro benzaldehyde, Phenyl propiolic acid, polyoxyethylene alcohols, quaternary amonium ethoxilated alcohols, and their fullyacid esters, polyethyleneimine, phosphalipides, sulfasalilic acid, linear alkyl sulfonate, sulfacetamide, Solochrome cyanin; sugars; sorbitol, sodium glucoheptonate, sodium glycerophosphate, sodium mercaptobenzotriazole, tetrahydropyranil amides, thiocarboxylic amides, thiocarbonyl-di-imidazole; thiocarbamid, thiohydantoin; thionine acetate, thiosalicilic acid, 2-thiolhistadine, thionine, thiodicarb, thioglycolic acid, thiodiglycols, thiodiglycolic acid, thiodipropionic acid, thioglycerol, dithiobenzoic acid, tetrabutylamonium, thiosulfone, thiosulfonic acid; thionicotineamide, thionyl chloride or bromide; thiourea; TIPA; tolyltriazole, triethanolamine; tri-benzylamine; 4,5,6, triaminopyrimidine; xylene cyanole.

While the foregoing is directed to the preferred embodiment of the present invention, other and further embodiments of the invention may be devised without departing from the basic scope thereof. The scope of the invention is determined by the claims which follow.

What is claimed is:

1. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container; wherein the substrate holder comprises:

i) a vacuum chuck having a substrate support surface; and

ii) an elastomer ring disposed around the substrate support surface, the elastomer ring contacting a peripheral portion of the substrate;

b) a cathode electrically contacting the substrate plating surface;

c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface; and

d) an anode electrically connected to the electrolyte.

2. The apparatus of claim 1 wherein the substrate holder further comprises:

iii) one or more bubble release ports having one or more openings adjacent an edge of the substrate supporting surface.

3. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container; wherein the substrate holder comprises:

i) a vacuum chuck having a substrate support surface; and

ii) a gas bladder disposed around the substrate support surface, the gas bladder adapted to contact a peripheral portion of the substrate;

b) a cathode electrically contacting the substrate plating surface;

c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface; and

d) an anode electrically connected to the electrolyte.

4. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container;

b) a cathode electrically contacting the substrate plating surface, wherein the cathode comprises a cathode contact member disposed at a peripheral portion of the substrate plating surface, the cathode contact member having a contact surface adapted to electrically contact the substrate surface, wherein the cathode contact member comprises a radial array of contact pins and a resistor connected in series with each contact pin;

c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface; and

d) an anode electrically connected to the electrolyte.

5. The apparatus of claim 4 wherein the cathode further comprises a sensor connected across each resistor to monitor the current flowing through the resistor.

6. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container;

b) a cathode electrically contacting the substrate plating surface;

c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface, wherein the electrolyte outlet is defined by a gap between a first surface on the substrate holder extending radially outward from the substrate plating surface and a surface of the electrolyte container; and

d) an anode electrically connected to the electrolyte.

7. The apparatus of claim 6 wherein the gap has a gap width between about 1 mm and about 30 mm.

8. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

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- a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container;
- b) a cathode electrically contacting the substrate plating surface;
- c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface;
- d) an anode electrically connected to the electrolyte; and
- e) a control electrode disposed in electrical contact with the electrolyte, the control electrode adapted to provide an adjustable electrical power.

9. The apparatus of claim 8 wherein the control electrode is disposed outside of the electrolyte container and in electrical contact with an outflowing electrolyte in the electrolyte outlet.

10. The apparatus of claim 8 wherein the control electrode comprises an array of electrode segments.

11. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

- a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container;
- b) a cathode electrically contacting the substrate plating surface;
- c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface;
- d) an anode electrically connected to the electrolyte; and
- e) a vibrator attached to the substrate holder, the vibrator transferring a vibration to the substrate holder.

12. The apparatus of claim 11 wherein the vibrator is adapted to vibrate the substrate holder in one or more directions.

13. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

- a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container;
- b) a cathode electrically contacting the substrate plating surface;
- c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface;
- d) an anode electrically connected to the electrolyte; and
- e) a sleeve insert disposed at a top portion of the electrolyte container, the sleeve insert defining the opening of the electrolyte container.

14. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

- a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container;
- b) a cathode electrically contacting the substrate plating surface;
- c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface;
- d) an anode electrically connected to the electrolyte; and
- e) a flow adjuster wedge disposed at a top portion within the electrolyte container.

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15. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

- a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container;
- b) a cathode electrically contacting the substrate plating surface;
- c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface;
- d) an anode electrically connected to the electrolyte; and
- e) a gas knife to supply a gas flow across the wafer plating surface to remove residual electrolyte.

16. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

- a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container;
- b) a cathode electrically contacting the substrate plating surface;
- c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface;
- d) an anode electrically connected to the electrolyte; and
- e) a wafer catcher disposed at a top portion within the electrolyte container.

17. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

- a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container;
- b) a cathode electrically contacting the substrate plating surface;
- c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface;
- d) an anode electrically connected to the electrolyte; and
- e) a reference electrode adapted to monitor the cathode and the anode.

18. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

- a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container;
- b) a cathode electrically contacting the substrate plating surface;
- c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface;
- d) an anode electrically connected to the electrolyte; and
- e) a rinsing solution supply selectively connected to the electrolyte inlet.

19. An apparatus for electrochemical deposition of a metal onto a substrate having a substrate plating surface, comprising:

- a) a substrate holder adapted to hold the substrate in a position wherein the substrate plating surface is exposed to an electrolyte in an electrolyte container;
- b) a cathode electrically contacting the substrate plating surface;

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- c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive the substrate plating surface;
 - d) an anode electrically connected to the electrolyte; and
 - e) gas bubble diverting vanes disposed within the electrolyte container to divert gas bubbles toward an electrolyte container sidewall.
20. A method for electrochemical deposition of a metal onto a substrate, comprising:
- a) providing an electrochemical deposition cell comprising:
 - 1) a substrate holder;
 - 2) a cathode electrically contacting a substrate plating surface;
 - 3) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive a substrate plating surface; and
 - 4) an anode electrically connected to an electrolyte;
 - b) applying electrical power to the cathode and the anode; and
 - c) flowing an electrolyte to contact the substrate plating surface, wherein the electrolyte flows between about 0.25 gallons per minute (gpm) to about 15 gpm.
21. A method for electrochemical deposition of a metal onto a substrate, comprising:
- a) providing an electrochemical deposition cell comprising:
 - 1) a substrate holder;
 - 2) a cathode electrically contacting a substrate plating surface;
 - 3) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive a substrate plating surface; and
 - 4) an anode electrically connected to an electrolyte;
 - b) applying electrical power to the cathode and the anode; and
 - c) flowing an electrolyte to contact the substrate plating surface;
- wherein the step of applying an electrical power to the cathode and the anode comprises:
- 1) applying a cathodic current density between about 5 mA/cm² and about 40 mA/cm² for about 1 second to about 240 seconds.
22. The method of claim 21 wherein the step of applying an electrical power to the cathode and the anode further comprises:
- 2) applying a dissolution reverse current between about 5 mA/cm² and about 80 mA/cm² for about 0.1 seconds to about 100 seconds.
23. A method for electrochemical deposition of a metal onto a substrate, comprising:
- a) providing an electrochemical deposition cell comprising:
 - 1) a substrate holder;
 - 2) a cathode electrically contacting a substrate plating surface;
 - 3) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive a substrate plating surface; and
 - 4) an anode electrically connected to an electrolyte;
 - b) applying electrical power to the cathode and the anode; and
 - c) flowing an electrolyte to contact the substrate plating surface;
- wherein the step of applying an electrical power to the cathode and the anode comprises:

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- 1) applying a cathodic current density between about 5 mA/cm² and about 40 mA/cm² for about 1 second to about 240 seconds;
 - 2) applying a dissolution reverse current between about 5 mA/cm² and about 80 mA/cm² for about 0.1 seconds to about 100 seconds;
 - 3) applying a cathodic current density between about 5 mA/cm² and about 40 mA/cm² for about 1 seconds to about 240 seconds; and
 - 4) repeating step 2 and step 3.
24. A method for electrochemical deposition of a metal onto a substrate, comprising:
- a) providing an electrochemical deposition cell comprising:
 - 1) a substrate holder;
 - 2) a cathode electrically contacting a substrate plating surface;
 - 3) an electrolyte container having an electrolyte inlet an electrolyte outlet and an opening adapted to receive a substrate plating surface; and
 - 4) an anode electrically connected to an electrolyte;
 - b) applying electrical power to the cathode and the anode;
 - c) flowing an electrolyte to contact the substrate plating surface;
 - d) providing a control electrode in electrical contact with an electrolyte of an electrochemical deposition cell; and
 - e) adjusting the electrical power provided by the control electrode during deposition.
25. The method of claim 24 wherein the electrical power provided by the control electrode is adjusted synchronously with a deposition/dissolution cycle of an electrochemical deposition process.
26. A method for electrochemical deposition of a metal onto a substrate, comprising:
- a) providing an electrochemical deposition cell comprising:
 - 1) a substrate holder;
 - 2) a cathode electrically contacting a substrate plating surface;
 - 3) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive a substrate plating surface; and
 - 4) an anode electrically connected to an electrolyte;
 - b) applying electrical power to the cathode and the anode;
 - c) flowing an electrolyte to contact the substrate plating surface; and
 - d) vibrating a component of the electrochemical deposition cell in one or more directions.
27. A method for electrochemical deposition of a metal onto a substrate, comprising:
- a) providing an electrochemical deposition cell comprising:
 - 1) a substrate holder;
 - 2) a cathode electrically contacting a substrate plating surface;
 - 3) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive a substrate plating surface; and
 - 4) an anode electrically connected to an electrolyte;
 - b) applying electrical power to the cathode and the anode;
 - c) flowing an electrolyte to contact the substrate plating surface; and
 - d) vibrating a component of the electrochemical deposition cell at a vibrational frequency between about 10

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Hz and about 20,000 Hz and a vibrational amplitude between about 0.5 micron and about 100,000 micron.

28. A method for electrochemical deposition of a metal onto a substrate, comprising:

- a) providing an electrochemical deposition cell comprising:
 - 1) a substrate holder; -
 - 2) a cathode electrically contacting a substrate plating surface;
 - 3) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive a substrate plating surface; and
 - 4) an anode electrically connected to an electrolyte;
- b) applying electrical power to the cathode and the anode;
- c) flowing an electrolyte to contact the substrate plating surface;
- d) rotating the substrate holder about a central axis through the substrate.

29. An apparatus for electrochemical deposition of a metal onto a substrate, comprising:

- a) a substrate holder comprising:
 - i) a vacuum chuck having a substrate support surface;
- and

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- ii) an elastomer ring disposed around the substrate support surface, the elastomer ring contacting a peripheral portion of the substrate.
- b) a cathode electrically contacting a substrate plating surface;
- c) an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive a substrate plating surface, wherein the electrolyte outlet is defined by a gap between a first surface extending radially outward from the substrate plating surface and a surface of the electrolyte container;
- d) an anode electrically connected to an electrolyte, the anode comprising:
 - i) a porous enclosure for flow of an electrolyte there-through;
 - ii) a metal disposed within the enclosure; and
 - iii) an electrode disposed within the enclosure;
- e) a control electrode in electrical contact with an electrolyte, the control electrode adapted to provide an adjustable electrical power; and
- f) a vibrator attached to the substrate holder, the vibrator adapted to transfer a vibration in one or more directions to the substrate holder.

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